

ABSTRACT

**SEMICONDUCTOR STACKED MULTI-PACKAGE MODULE
HAVING INVERTED SECOND PACKAGE
AND ELECTRICALLY SHIELDED FIRST PACKAGE**

A semiconductor multi-package module has an inverted second package stacked over a first package, in which the stacked packages are electronically interconnected by wire bonds, and in which at least one of the packages is provided with an electrical shield. Also, a method for making a semiconductor multi-package module, by providing a lower molded package including a lower substrate and a die and having a shield, affixing an upper molded package including an upper substrate in inverted orientation onto an upper surface of the lower package, and forming z-interconnects between the upper and lower substrates. Where the shield is situated above the lower package substrate, the inverted upper package is affixed onto an upper surface of the shield.